

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6223xxxx9R-G
Typical Mass: 1 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.090	Silicon	89600	7440-21-3
		- Arsenic	10	7440-38-2
Lead pad	0.099	Nickel	98500	7440-02-0
		Silver	9400	7440-22-4
		Gold	1100	7440-57-5
Die attach	0.002	Silica	2200	60676-86-0
		Epoxy Resin	1700	—
Bonding wire	0.047	Gold	47300	7440-57-5
Resin	0.675	Silica	675200	60676-86-0
		Epoxy Resin	45000	—
		Phenol Resin	30100	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."